



Product Change Notification

Change Notification #: 115993 - 00

Change Title: Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS,
Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS,
Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Low Profile 100HFA018LS,
Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Standard 100HFA018FS,
PCN 115993-00, Product Design, Label Firmware Update, Regulatory Label Change, Capacitor Value Change

Date of Publication: December 13, 2017

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	January 15, 2018
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The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	Product Description
100HFA016LS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS
100HFA016FS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS
100HFA018LS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Low Profile 100HFA018LS
100HFA018FS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Standard 100HFA018FS

Overview of Changes:

Change 1: The HFI adapter firmware will be updated to version 1.5.2.

Change 2: Regulatory and Compliance Certifications were successfully acquired from Ukraine and BSMI (Taiwan). The regulatory label will be updated to reflect the new RoHS certifications.

Change 3: The voltage regulator circuit capacitor values will be changed to improve margin, per revised guidance in the supplier's datasheet updates.

Product Change Details:

Change 1: The HFI adapter firmware version will be updated from 1.3.0 to 1.5.2. This includes the file changes shown in the following detail table. See version 1.5.2 Release Note document J80202 for further details.

DESCRIPTION	FROM		TO	
	FILE NAME	VERSION	FILE NAME	VERSION
HFI1 UEFI Option ROM	HfiPcieGen3_1.3.0.0.0.efi	1.3.0.0.0	HfiPcieGen3_1.5.2.0.0.efi	1.5.2.0.0
UEFI UNDI Loader	HfiPcieGen3Loader_1.3.0.0.0.rom	1.3.0.0.0	HfiPcieGen3Loader_1.5.2.0.0.rom	1.5.2.0.0
HFI1 SMBus Microcontroller Firmware (Thermal Monitor)	CHF_SMBUS_MC_10.2.1.0.3.main.signed.bin	10.2.1.0.3	CHF_SMBUS_MC_10.4.0.0.146.main.signed.bin	10.4.0.0.146

Change 2: The regulatory label will be updated with new RoHS certifications for Ukraine and BSMI (Taiwan). The regulatory label updates are shown in **Figure 1** through **Figure 4** below.

Figure 1. 100HFA016 Regulatory Label, Before

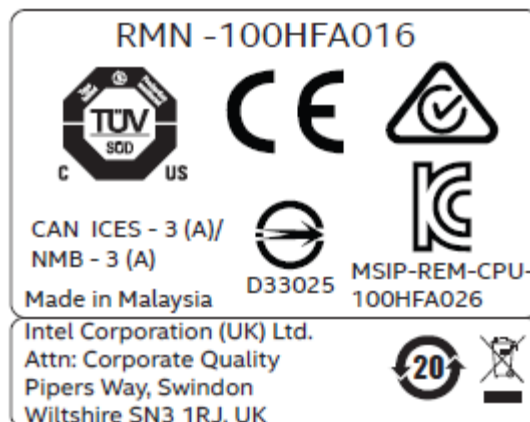


Figure 2. 100HFA016 Regulatory Label, After

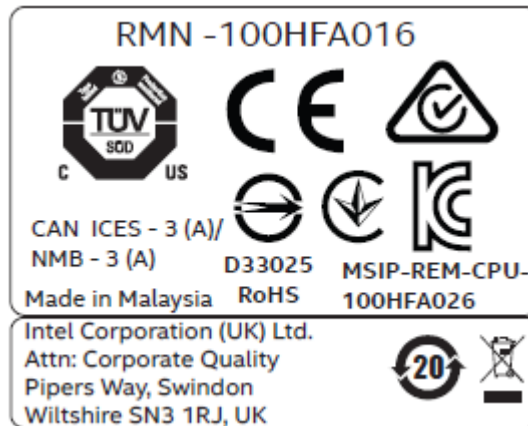


Figure 3. 100HFA018 Regulatory Label, Before

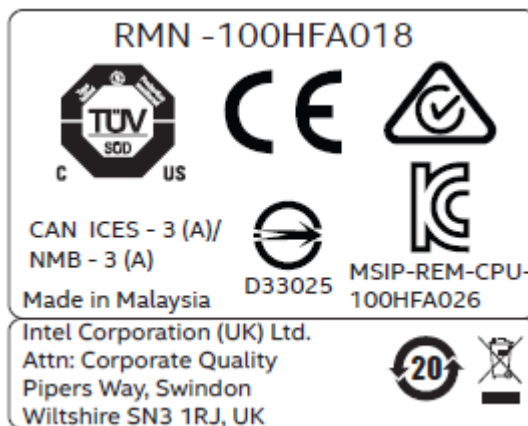
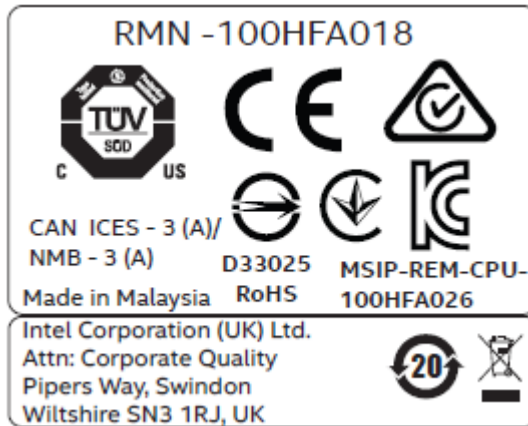


Figure 4. 100HFA018 Regulatory Label, After



Change 3: The voltage regulator supplier has updated its product datasheet with component and part configuration recommendations that are intended to improve the part's operating margin. As a result of this guidance, the value of three capacitors used by the voltage regulator circuit will increase from 4.7uF to 10uF to provide improved operational margin.

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.

There is no change to the Intel Material Master (MM) numbers.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

* Other names and brands may be claimed as the property of others

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AS	Post Change AS
100HFA016LS	948159	15	16	J10549-024	J10549-025	J10548-024	J10548-025
100HFA016FS	945671	05	06	J29320-005	J29320-006	J29321-005	J29321-006
100HFA018LS	945670	11	12	J12508-014	J12508-015	J12507-014	J12507-015
100HFA018FS	945672	04	05	J31082-004	J31082-005	J31081-004	J31081-005

PCN Revision History:

Date of Revision:

December 13, 2017

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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